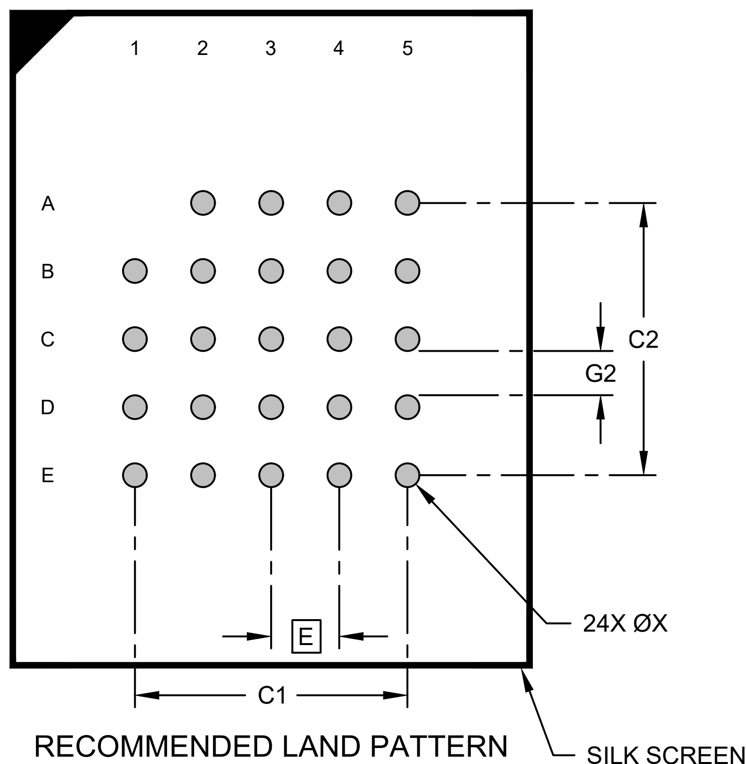
24-Ball Thin-Profile Fine-Pitch Ball Grid Array Package (8SW) - 6x8x1.2 mm Body [TFBGA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.00 BSC		
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Diameter (Xnn)	X			0.35
Contact Pad to Contact Pad (Xnn)	G2	0.65		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to the current industry standard IPC-7093.